

AMENDMENT(S) TO THE SPECIFICATION

Please replace the title of the invention beginning at page 1, line 1, with the following rewritten title:

AN INTERFACE DEVICE PROVIDING AN INTERFACE BETWEEN TESTING
EQUIPMENT AND AN INTEGRATED CIRCUIT

Please replace the paragraph beginning at page 1, line 7, with the following rewritten paragraph:

BACKGROUND OF THE INVENTION

A probe card is used in semiconductor wafer fabrication and/or packaging facilities to test the integrity of every semiconductor chip (or die) produced. The process of testing involves testing equipment referred to as “probers” and an interface device that couples the testing equipment to the die to be tested. The interface device is commonly known as a “probe card”. The probe card generally comprises a large number of probes, which take the form of pins. The pins are arranged on a printed circuit board, or other support structure, in a pattern that corresponds to the layout of the bonding pads on the die to be tested. Each die requires a probe card with a pin pattern that is specific to the layout of the bond pads on the die.

Please replace the paragraph beginning at page 2, line 25, with the following rewritten paragraph:

BRIEF SUMMARY OF THE INVENTION

In accordance with a first aspect of the present invention, an interface device for providing an interface between testing equipment and an integrated circuit to be tested comprises a body member; a number of elongate contact members, each elongate contact member comprising a contact end, adapted to contact a bond pad of an integrated circuit to be tested, and a body portion coupled to the body member; and a guide member mounted on the body member, the guide member comprising a substantially planar member having a number of apertures therein, the contact end of each elongate member extending through a respective aperture in the guide member, and the width of each contact end being less than the width of the respective aperture to

permit lateral movement of each contact end within the respective aperture.

Please replace the paragraph beginning at page 6, line 21, with the following rewritten paragraph:

BRIEF DESCRIPTION OF THE SEVERAL VIEWS OF THE DRAWINGS

Figure 1 is a schematic perspective view of a section of an interface device including a guide member;

Figure 2 is a side view of a portion of the interface device; and

Figure 3 is a schematic view of apparatus for forming apertures in the guide member forming part of the interface device shown in Figures 1 and 2.

Please replace the paragraph beginning at page 7, line 3, with the following rewritten paragraph:

DETAILED DESCRIPTION OF THE INVENTION

Figure 1 shows a schematic view of a portion of a probe card 2. The probe card 2 includes a ring 1 formed from ceramic, aluminum or titanium, a guide member in the form of a glass wafer 3 and a number of contact pins 5 mounted on the ring 1 by means of a ceramic shim 6 and epoxy resin 7.